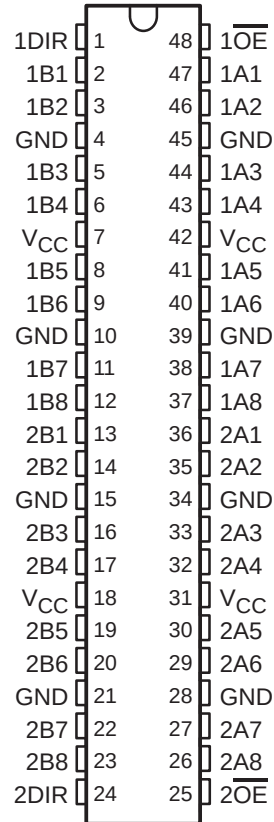


SN54ABTH16245, SN74ABTH16245 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS662I – MARCH 1996 – REVISED MARCH 1999

- Members of the Texas Instruments *Widebus™* Family
- State-of-the-Art *EPIC-II B™* BiCMOS Design Significantly Reduces Power Dissipation
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- High-Impedance State During Power Up and Power Down
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs ($-32\text{-mA } I_{OH}$, $64\text{-mA } I_{OL}$)
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

SN54ABTH16245 . . . WD PACKAGE
SN74ABTH16245 . . . DGG, DGV, OR DL PACKAGE
(TOP VIEW)



description

The 'ABTH16245 devices are 16-bit noninverting 3-state transceivers that provide synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the devices so that the buses are effectively isolated.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN54ABTH16245 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ABTH16245 is characterized for operation from -40°C to 85°C .



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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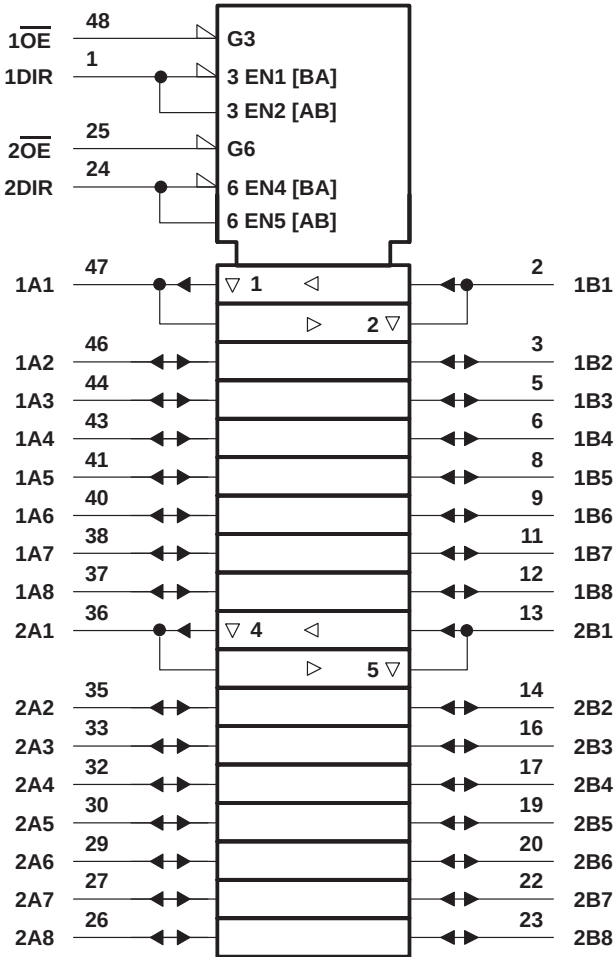
SN54ABTH16245, SN74ABTH16245
16-BIT BUS TRANSCEIVERS
WITH 3-STATE OUTPUTS

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FUNCTION TABLE
(each 8-bit section)

INPUTS		OPERATION
OE	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

The logic diagram for the 2A1 channel shows the following components and connections:

- Inputs:** 2DIR (pin 24) and 2A1 (pin 36).
- Logic:** Two AND gates and two inverters.
 - The first AND gate has inputs from 2DIR and 2OE (pin 25).
 - The second AND gate has inputs from 2A1 and 2OE.
 - The output of the first AND gate is connected to the input of the first inverter.
 - The output of the second AND gate is connected to the input of the second inverter.
 - The output of the first inverter is connected to the input of the second AND gate.
 - The output of the second inverter is connected to the input of the first AND gate.
- Outputs:** 2B1 (pin 13) and two outputs connected to other channels (pins 14 and 15).

3

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A = 25°C			SN54ABTH16245		SN74ABTH16245		UNIT
				MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	
V _{IK}		V _{CC} = 4.5 V, I _I = -18 mA				-1.2		-1.2		-1.2	V
V _{OH}		V _{CC} = 4.5 V, I _{OH} = -3 mA		2.5			2.5		2.5		V
		V _{CC} = 5 V, I _{OH} = -3 mA		3			3		3		
		V _{CC} = 4.5 V	I _{OH} = -24 mA	2			2				
			I _{OH} = -32 mA	2*					2		
V _{OL}		V _{CC} = 4.5 V	I _{OL} = 48 mA			0.55		0.55			V
			I _{OL} = 64 mA			0.55*				0.55	
V _{hys}					100						mV
I _I	Control inputs	V _{CC} = 5.5 V, V _I = V _{CC} or GND				±1		±1		±1	μA
	A or B ports					±100		±100		±100	
I _I (hold)		V _{CC} = 4.5 V	V _I = 0.8 V	100			100		100		μA
			V _I = 2 V	-100			-100		-100		
I _{OZPU}		V _{CC} = 0 to 1.9 V	V _O = 0.5 V to 2.7 V, OE = X			±50**		±50**			μA
		V _{CC} = 0 to 2.1 V				±50				±50	
I _{OZPD}		V _{CC} = 1.9 V to 0	V _O = 0.5 V to 2.7 V, OE = X			±50**		±50**			μA
		V _{CC} = 2.1 V to 0				±50				±50	
I _{off}		V _{CC} = 0, V _I or V _O ≤ 4.5 V				±100				±100	μA
I _{CEX}		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μA
I _O [‡]		V _{CC} = 5.5 V, V _O = 2.5 V		-50	-100	-180	-50	-180	-50	-180	mA
I _{CC}	A or B ports	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND	Outputs high			2		2		2	mA
			Outputs low			32		32		32	
			Outputs disabled			2		2		2	
ΔI _{CC} [§]		V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				1.5		1.5		1.5	mA
C _i	Control inputs	V _I = 2.5 V or 0.5 V				3					pF
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V				6					pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.

** On products compliant to MIL-PRF-38535, this parameter is not production tested.

† All typical values are at V_{CC} = 5 V.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

SN54ABTH16245, SN74ABTH16245
16-BIT BUS TRANSCEIVERS
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABTH16245					UNIT
			V _{CC} = 5 V, T _A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t _{PLH}	A or B	B or A	1	2.2	3.6	0.5	4.1	ns
t _{PHL}			1	2.3	3.8	0.5	4.4	
t _{PZH}	$\overline{OE}$	B or A	1	3.6	5.2	0.8	6.4	ns
t _{PZL}			1	3.7	6.1	0.9	6.5	
t _{PHZ}	$\overline{OE}$	B or A	2	4.4	6.7	1.3	7.9	ns
t _{PLZ}			1.5	3.3	4.7	1.4	5.6	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABTH16245					UNIT
			V _{CC} = 5 V, T _A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t _{PLH}	A or B	B or A	1	2.2	3.4	1	3.9	ns
t _{PHL}			1	2.3	3.7	1	4.2	
t _{PZH}	$\overline{OE}$	B or A	1	3.6	5.2	1	6.3	ns
t _{PZL}			1	3.7	5.4	1	6.4	
t _{PHZ}	$\overline{OE}$	B or A	2	4.4	5.8	2	6.3	ns
t _{PLZ}			1.5	3.3	4.7	1.5	5.2	

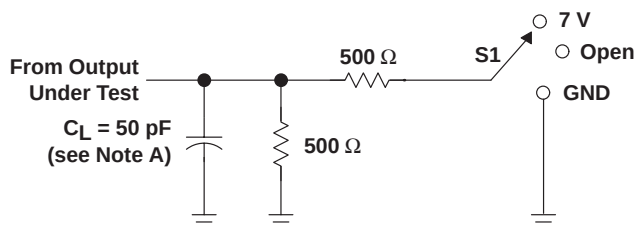
SN54ABTH16245, SN74ABTH16245

16-BIT BUS TRANSCEIVERS

WITH 3-STATE OUTPUTS

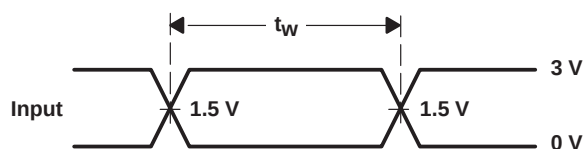
SCBS662I – MARCH 1996 – REVISED MARCH 1999

PARAMETER MEASUREMENT INFORMATION

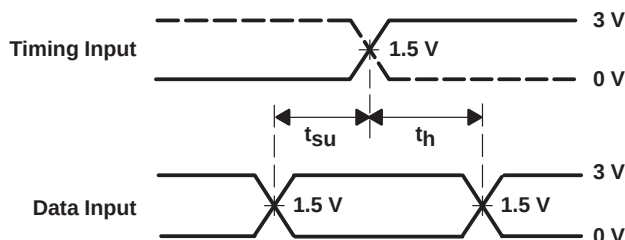


LOAD CIRCUIT

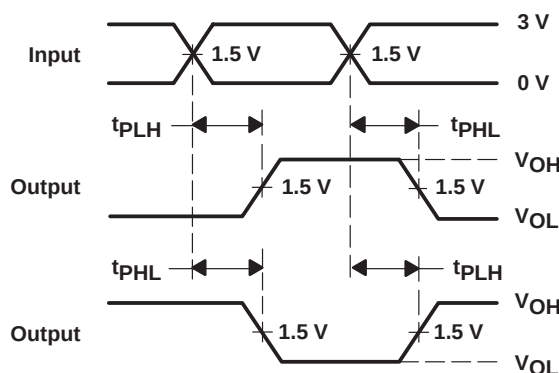
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



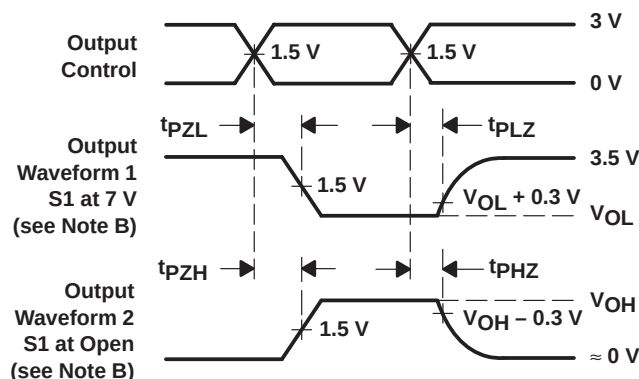
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
74ABTH16245DGGRG4	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
74ABTH16245DGGRG4.B	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DGGR	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DGGR.B	Active	Production	TSSOP (DGG) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DGVR	Active	Production	TVSOP (DGV) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AM245
SN74ABTH16245DGVR.B	Active	Production	TVSOP (DGV) 48	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AM245
SN74ABTH16245DL	Active	Production	SSOP (DL) 48	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DL.B	Active	Production	SSOP (DL) 48	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DLR	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DLR.B	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DLRG4	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245
SN74ABTH16245DLRG4.B	Active	Production	SSOP (DL) 48	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH16245

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ABTH16245DGGRG4	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABTH16245DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABTH16245DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74ABTH16245DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74ABTH16245DLRG4	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74ABTH16245DGGRG4	TSSOP	DGG	48	2000	356.0	356.0	45.0
SN74ABTH16245DGGR	TSSOP	DGG	48	2000	356.0	356.0	45.0
SN74ABTH16245DGVR	TVSOP	DGV	48	2000	353.0	353.0	32.0
SN74ABTH16245DLR	SSOP	DL	48	1000	356.0	356.0	53.0
SN74ABTH16245DLRG4	SSOP	DL	48	1000	356.0	356.0	53.0

TUBE

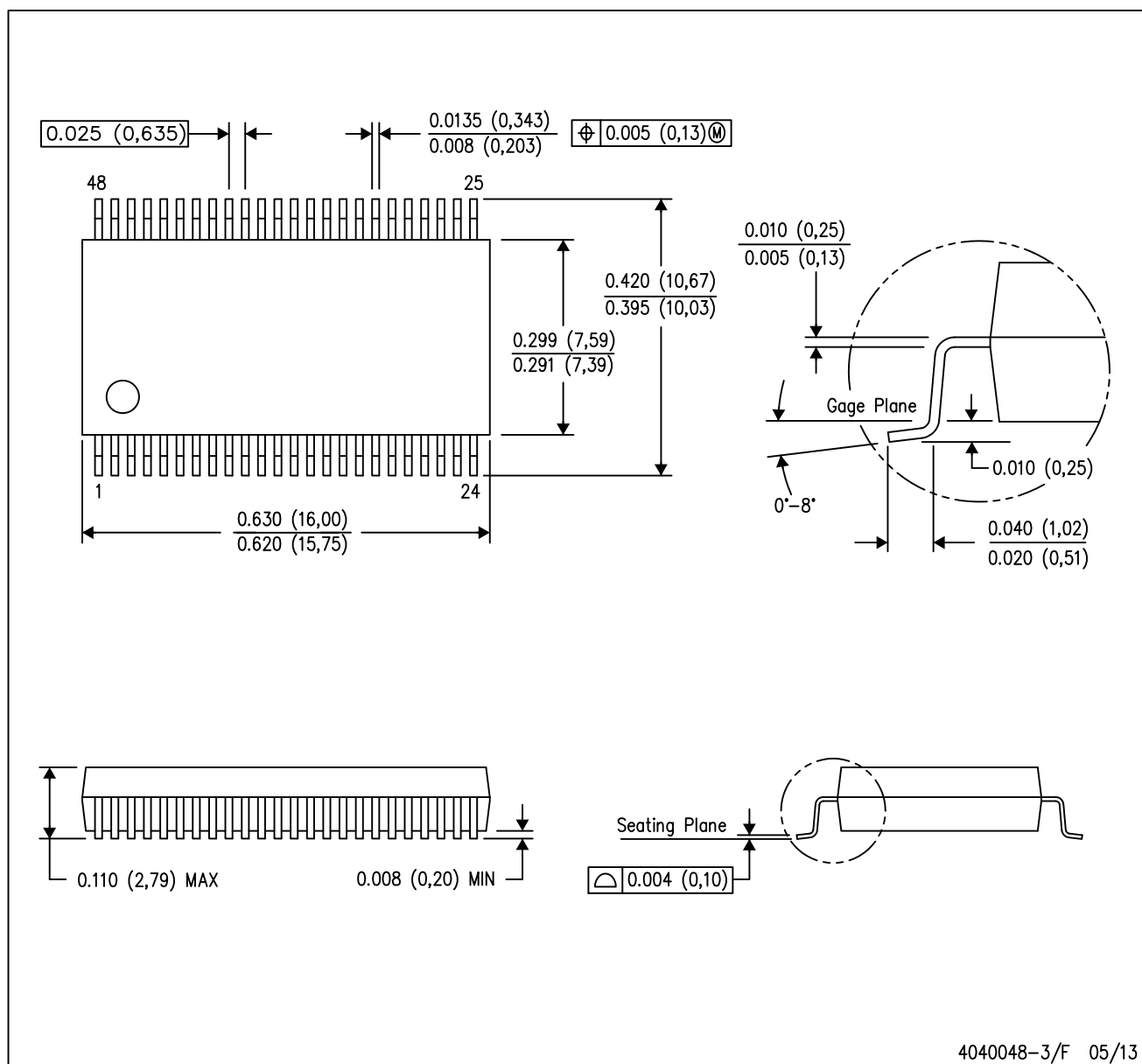


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74ABTH16245DL	DL	SSOP	48	25	473.7	14.24	5110	7.87
SN74ABTH16245DL.B	DL	SSOP	48	25	473.7	14.24	5110	7.87

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE

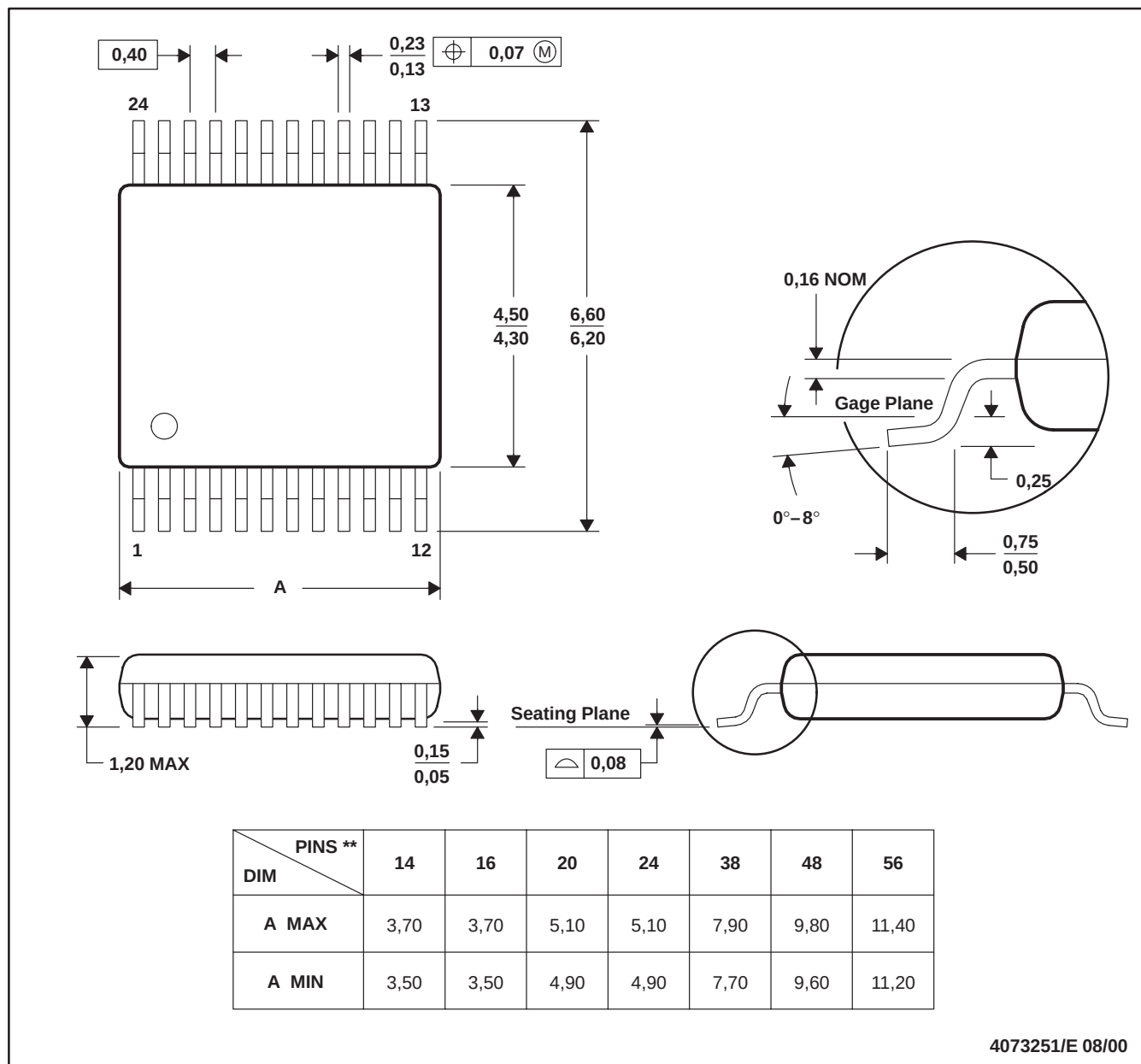


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MO-118

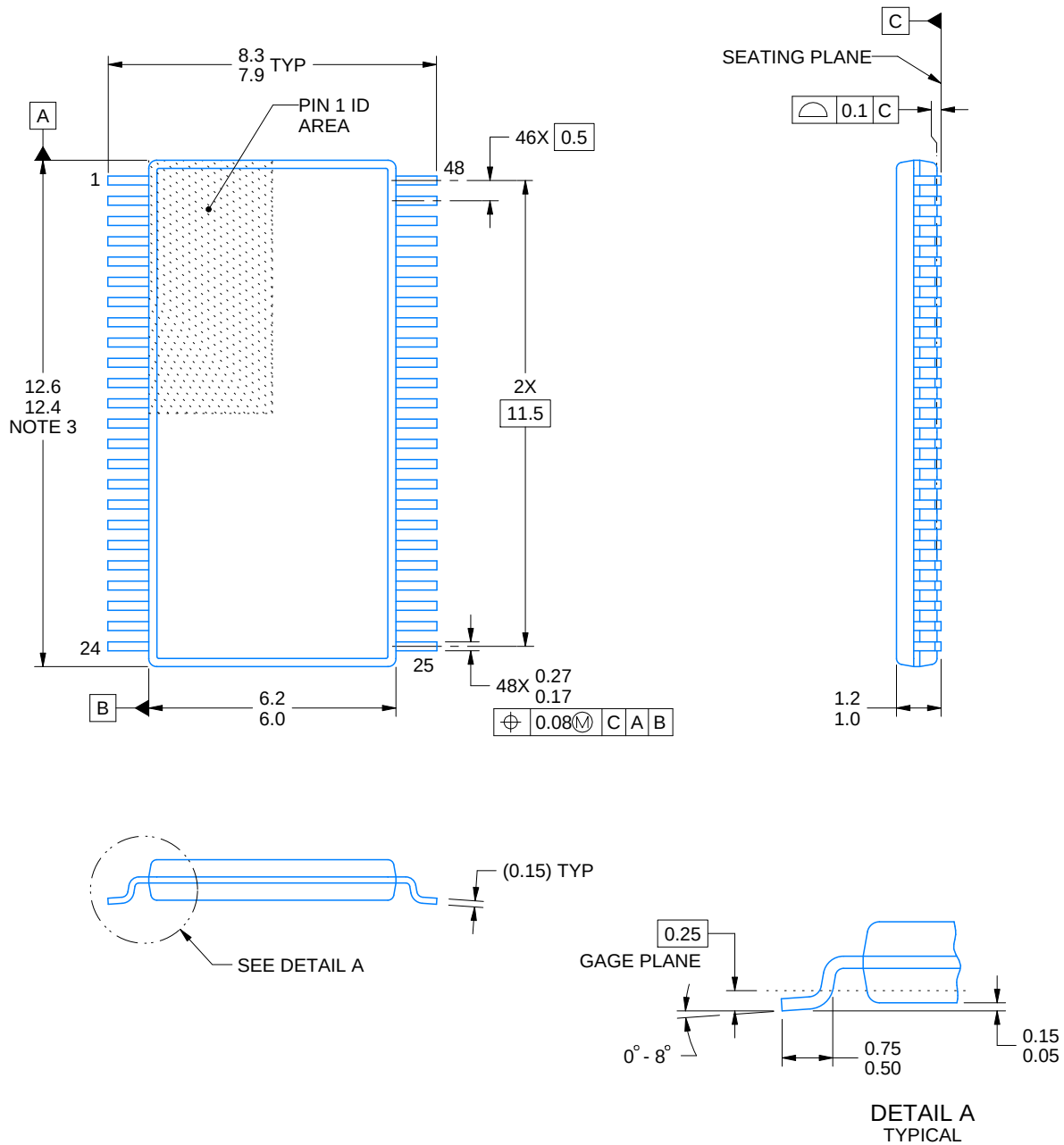
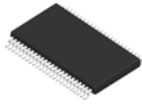
DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194



4214859/B 11/2020

NOTES:

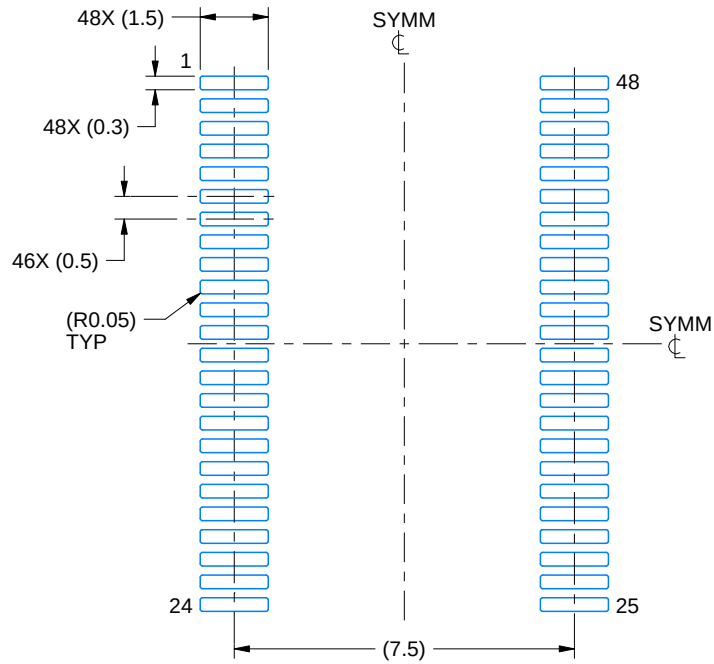
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

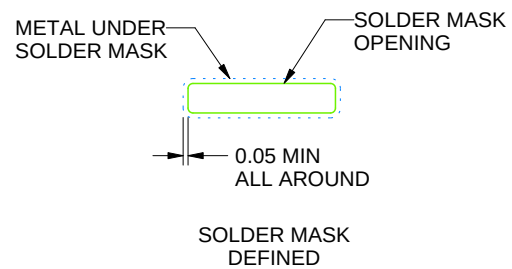
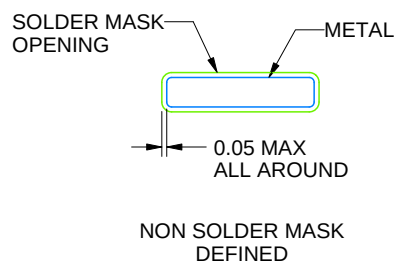
DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4214859/B 11/2020

NOTES: (continued)

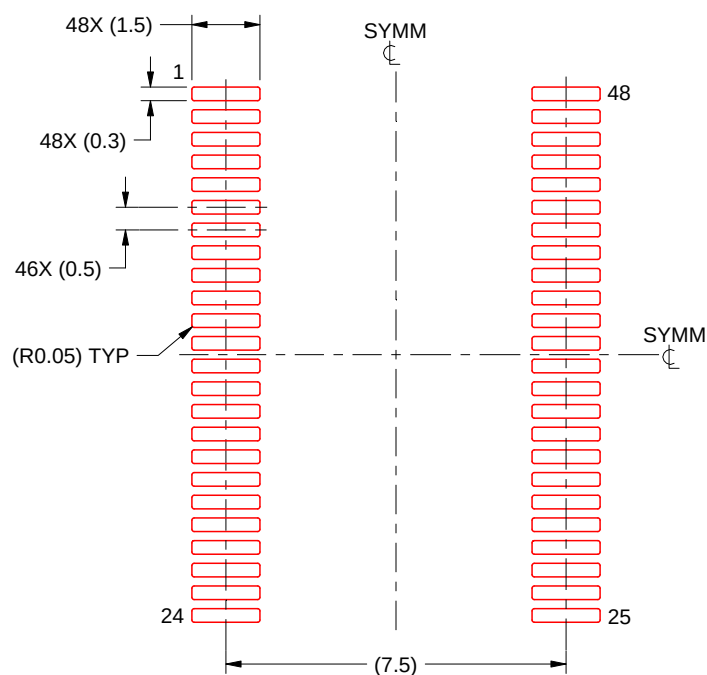
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

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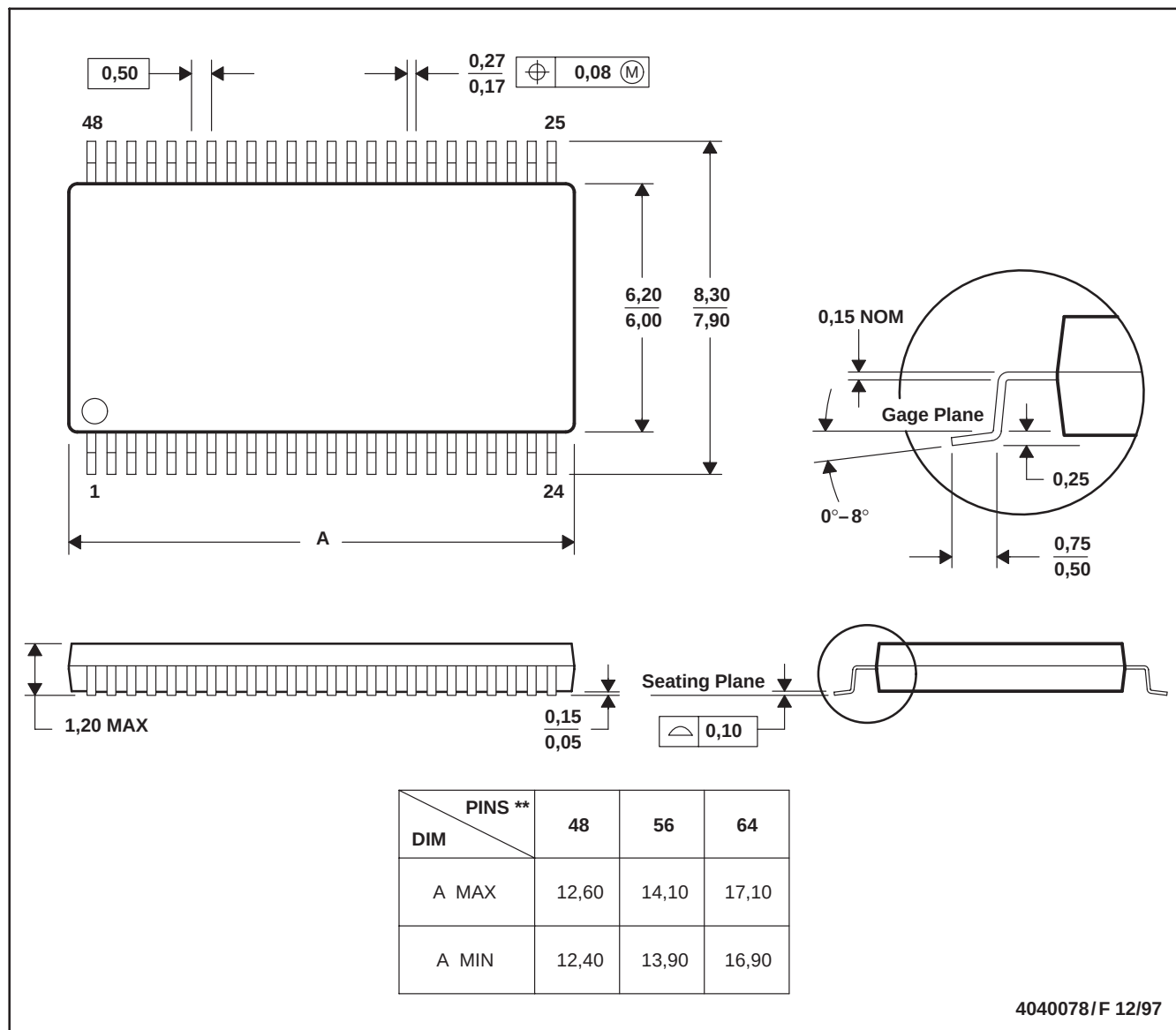
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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